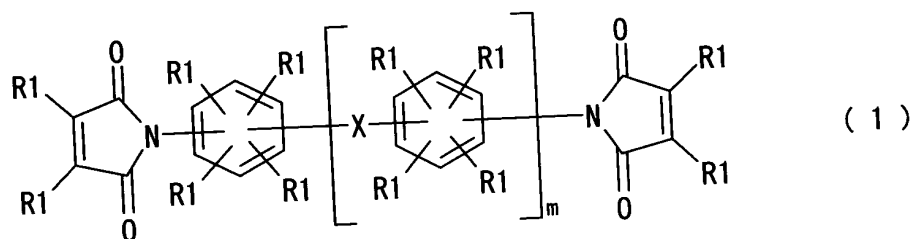


# ABSTRACT

A heat resistance resin composition having superb low-temperature adhesiveness and a polyimide/metal laminate which is superior in solder heat resistance and hardly generates swelling when forming a Au-Sn bond or Au-Au bond, which are used for lead-free soldering and COF packaging. A metal laminate comprising a layer comprises a resin composition prepared by compounding a bismaleimide compound represented by the following formula (1) in a polyamic acid and/or a polyimide:



wherein m denotes an integer of 0 or more, each X independently represent O, SO<sub>2</sub>, S, CO, CH<sub>2</sub>, C(CH<sub>3</sub>)<sub>2</sub>, C(CF<sub>3</sub>)<sub>2</sub> or a direct bond and each R<sub>1</sub> independently represents a hydrogen atom, a halogen atom or a hydrocarbon group and is independent of any other R<sub>1</sub> as to the substitution position on the benzene ring; and a metal foil layer, wherein the layer of the resin composition is formed on at least one surface of the metal foil layer. A resin composition for a metal laminate is also disclosed.